CD74HCT4514, CD74HCT4515 4-LINE TO 16-LINE DECODERS/DEMULTIPLEXERS WITH INPUT LATCHES

SCHS314D - MAY 2002 - REVISED SEPTEMBER 2004

- 4.5-V to 5.5-V V_{CC} Operation
- Fanout (Over Temperature Range)
 - Standard Outputs . . . 10 LSTTL Loads
 - Bus-Driver Outputs . . . 15 LSTTL Loads
- Wide Operating Temperature Range of –55°C to 125°C
- Balanced Propagation Delays and Transition Times
- Significant Power Reduction Compared to LSTTL Logic ICs
- HCT Types
 - Direct LSTTL Input Logic Compatibility,
 V_{IL} = 0.8 V (Max), V_{IH} = 2 V (Min)
 - CMOS Input Compatibility, I_I ≤ 1 μA at V_{OL}, V_{OH}

CD74HCT4514...E PACKAGE CD74HCT4515...E OR EN PACKAGE (TOP VIEW) 24 🛮 V_{CC} LE 23 | E A0 [22 A3 A1 21 🛮 A2 Y7 **∏** 4 20 N Y10 Y6 ∏ 5 Y5 🛮 6 19 Y11 18**∏** Y8 Y4 17 | Y9 Y3 [9 16 Y14 Y1 II 15 Y15 Y2 **∏** 10 14 Y12 Y0 🛮 11 13 ∏ GND [] Y13

description/ordering information

The CD74HCT4514 and CD74HCT4515 are high-speed silicon-gate devices consisting of a 4-bit strobed latch and a 4-line to 16-line decoder. The selected output is enabled by a low on the enable (\overline{E}) input. A high on \overline{E} inhibits selection of any output. Demultiplexing is accomplished by using \overline{E} as the data input and the select inputs (A0–A3) as addresses. \overline{E} also serves as a chip select when these devices are cascaded.

When the latch enable ($\overline{\text{LE}}$) is high, the output follows changes in the inputs (see decode function table). When $\overline{\text{LE}}$ is low, the output is isolated from changes in the input and remains at the level (high for the '4514, low for the '4515) it had before the latch was enabled.

ORDERING INFORMATION

TA	PAC	KAGET	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – F	Tube	CD74HCT4514E	CD74HCT4514E
–55°C to 125°C	FDIF - L	Tube	CD74HCT4515E	CD74HCT4515E
	PDIP – EN	Tube	CD74HCT4515EN	CD74HCT4515EN

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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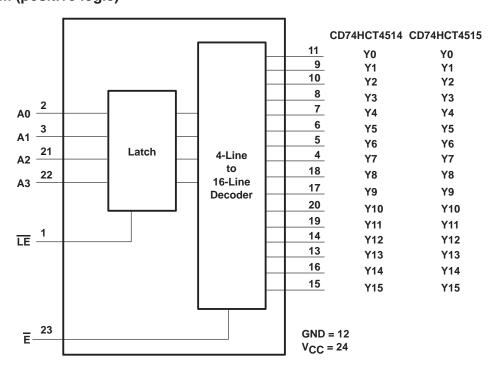


DECODE FUNCTION TABLE $(\overline{LE} = H)$

Ē	D	ECODE	R INPUT	s	ADDRESSED OUTPUT
E	А3	A2	A 1	Α0	CD74HCT4514 = H CD74HCT4515 = L
L	L	L	L	L	Y0
L	L	L	L	Н	Y1
L	L	L	Н	L	Y2
L	L	L	Н	Н	Y3
L	L	Н	L	L	Y4
L	L	Н	L	Н	Y5
L	L	Н	Н	L	Y6
L	L	Н	Н	Н	Y7
L	Н	L	L	L	Y8
L	Н	L	L	Н	Y9
L	Н	L	Н	L	Y10
L	Н	L	Н	Н	Y11
L	Н	Н	L	L	Y12
L	Н	Н	L	Н	Y13
L	Н	Н	Н	L	Y14
L	Н	Н	Н	Н	Y15
Н	Х	Х	Х	Х	All outputs = L, CD74HCT4514 All outputs = H, CD74HCT4515

H = high, L = low, X = don't care

logic diagram (positive logic)



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	\dots -0.5 V to 7 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) (see Note 1)	±20 mA
Output clamp current, I _{OK} (V _O < 0 or V _O > V _{CC}) (see Note 1)	±20 mA
Continuous output drain current per output, I_O ($V_O = 0$ to V_{CC})	±25 mA
Continuous output source or sink current per output, $I_O(V_O = 0 \text{ to } V_{CC})$	±25 mA
Continuous current through V _{CC} or GND	±50 mA
Package thermal impedance, θ _{JA} (see Note 2): E package	67°C/W
EN package	67°C/W
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	265°C
Storage temperature range, T _{stg}	65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions (see Note 3)

		T _A = 2	25°C	T _A = -		T _A = -40°C TO 85°C		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
VCC	Supply voltage	4.5	5.5	4.5	5.5	4.5	5.5	V
VIH	High-level input voltage	2		2		2		V
VIL	Low-level input voltage		8.0		0.8		0.8	V
VI	Input voltage	0	VCC	0	VCC	0	VCC	V
VO	Output voltage	0	VCC	0	VCC	0	VCC	V
Δt/Δν	Input transition rise or fall rate		500		500		500	ns

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CON	VCC	T _A = 25°C		T _A = -55°C TO 125°C		T _A = -40°C TO 85°C		UNIT	
				MIN	MAX	MIN	MAX	MIN	MAX	V
V	M. Maran Mar	I _{OH} = -20 μA	451/	4.4		4.4		4.4		.,
VOH	VI = VIH or VIL	$I_{OH} = -4 \text{ mA}$	4.5 V	3.98		3.7		3.84		V
V	V V 22V	I _{OL} = 20 μA	45.77		0.1		0.1		0.1	.,
V _{OL}	$V_I = V_{IH}$ or V_{IL}	I _{OL} = 4 mA	4.5 V		0.26		0.4		0.33	V
ΙĮ	$V_I = V_{CC}$ or 0		5.5 V		±0.1		±1		±1	μΑ
lcc	$V_I = V_{CC}$ or 0,	I _O = 0	5.5 V		8		160		80	μΑ
∆lCC [‡]	One input at V _{CC} – 2.1 V,	Other inputs at 0 or V _{CC}	4.5 V to 5.5 V		360		490		450	μΑ
Ci					10		10		10	pF

[‡] Additional quiescent supply current per input pin, TTL inputs high, 1 unit load. For dual-supply systems, theoretical worst-case (V_I = 2.4 V, V_{CC} = 5.5 V) specification is 1.8 mA.



NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

^{2.} The package thermal impedance is calculated in accordance with JESD 51-3.

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HCT INPUT LOADING TABLE

INPUT	UNIT LOAD
A0-A3	0.15
LE	0.85
Ē	0.3

Unit load is ΔI_{CC} limit specified in electrical characteristics table (e.g., 360 μA max at 25°C).

timing requirements over recommended operating free-air temperature range, V_{CC} = 4.5 V, C_L = 15 pF (unless otherwise noted) (see Figure 1)

		T _A = 2	25°C	T _A = -	.55°C 25°C	T _A = -40°C TO 85°C		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
t _W	Pulse duration, LE high	30		45		38		ns
t _{su}	Setup time, data before LE↓	20		30		25		ns
th	Hold time, data after LE↓	5		5		5		ns

switching characteristics over recommended operating free-air temperature range, V_{CC} = 4.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	TO (OUTPUT)	LOAD CAPACITANCE	T _A = 2	25°C	T _A = -		T _A = -		UNIT
	(INPUT)	(001P01)	CAPACITANCE	MIN	MAX	MIN	MAX	MIN	MAX	
	A0-A3				55		83		69	
t _{pd}	LE	Υ	C _L = 50 pF		50		75		63	ns
	Ē				40		60		50	
t _t		Υ	C _L = 50 pF		15		22		19	ns

operating characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$

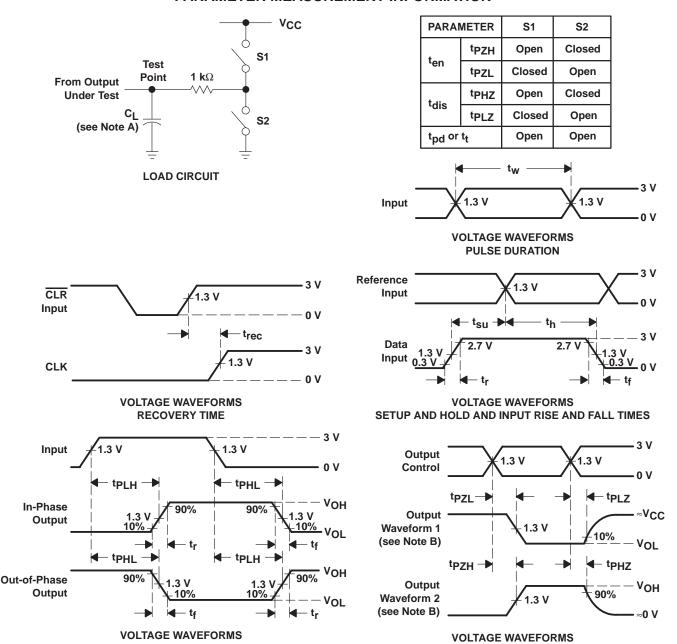
	PARAMETER	TYP	UNIT
ſ	C _{pd} Power dissipation capacitance	75	pF



OUTPUT ENABLE AND DISABLE TIMES

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PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_I includes probe and test-fixture capacitance.

PROPAGATION DELAY AND OUTPUT TRANSITION TIMES

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O = 50 \Omega$, $t_f = 6 \text{ ns}$, $t_f = 6 \text{ ns}$.
- D. For clock inputs, f_{max} is measured with the input duty cycle at 50%.
- E. The outputs are measured one at a time, with one input transition per measurement.
- F. tpLZ and tpHZ are the same as tdis.
- G. tpzL and tpzH are the same as ten.
- H. tplH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms







17-May-2014

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish (6)	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
CD74HCT4514E	ACTIVE	PDIP	N	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-55 to 125	CD74HCT4514E	Samples
CD74HCT4514EE4	ACTIVE	PDIP	N	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-55 to 125	CD74HCT4514E	Samples
CD74HCT4515E	ACTIVE	PDIP	N	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-55 to 125	CD74HCT4515E	Samples
CD74HCT4515EE4	ACTIVE	PDIP	N	24		TBD	Call TI	Call TI	-55 to 125		Samples
CD74HCT4515EN	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-55 to 125	CD74HCT4515EN	Samples
CD74HCT4515ENE4	ACTIVE	PDIP	NT	24		TBD	Call TI	Call TI	-55 to 125		Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.



PACKAGE OPTION ADDENDUM

17-May-2014

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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